

Title (en)

Process for the preparation of a heating assembly and tool including the heating assembly

Title (de)

Verfahren zur Herstellung einer Heizanordnung und Werkzeug umfassend die Heizanordnung

Title (fr)

Procédé de fabrication d'une installation de chauffage et outil comprenant l'installation de chauffage

Publication

**EP 2680667 A1 20140101 (DE)**

Application

**EP 13003263 A 20130626**

Priority

DE 102012012968 A 20120629

Abstract (en)

The method involves inserting an insulated heating wire (4) directly into a groove (6) formed along the surface (3) of a base element (2). The groove comprising heating wire is filled with the consistent sealing material (7) by a cold gas spraying, and closed. The heating wire has a round cross section with a diameter of a preset value. A nut is arranged at the bottom of the heating wire. The individual layers (5) of the heating wire comprise different spacing. Independent claims are included for the following: (1) a heating assembly; and (2) a tool for shaping and/or heating up a component.

Abstract (de)

Die Erfindung betrifft ein Verfahren zur Herstellung einer Heizanordnung (1), umfassend die folgenden Schritte: Bereitstellen eines Basiselementes (2) mit zumindest einer Nut (6), Einlegen zumindest eines Heizelementes (4) in die Nut (6), und stoffschlüssiges Verschließen der Nut (6) und gleichzeitiges Einschließen des Heizelementes (4) durch Pulverspritzen, vorzugsweise Kaltgasspritzen.

IPC 8 full level

**H05B 3/26** (2006.01)

CPC (source: EP)

**H05B 3/26** (2013.01); **H05B 2203/003** (2013.01); **H05B 2203/013** (2013.01); **H05B 2203/017** (2013.01)

Citation (search report)

- [A] EP 0962961 A2 19991208 - NGK INSULATORS LTD [JP]
- [A] JP 2004071182 A 20040304 - NGK SPARK PLUG CO
- [A] JP S5230931 A 19770309 - IKEDA YASUO

Designated contracting state (EPC)

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Designated extension state (EPC)

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